ABSTRACT OF THE DISCLOSURE

A method of making a microelectronic assembly includes juxtaposing a first element, such as a dielectric sheet having conductive leads thereon with a second element, such as a semiconductor chip, having contact thereon, and wire bonding the conductive leads on the first element to the contacts on the second element so that elongated bonding wires extend between the conductive leads and the contacts. After the wire bonding step, the first and second elements are moved through a pre-selected displacement relative to one another so as to deform the bonding wires. A flowable dielectric material may be introduced between the first and second elements and around the bonding wires during or after the moving step. The flowable material may be cured to form an encapsulant around at least a portion of the bonding wires.

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